





Absolute Maximum Ratings at Ta=25℃

Parameter	MAX.	Unit	
Power Dissipation	150	mW	
Continuous Forward Current	100	mA	
Peak Forward Current *1	1.0	A	
Reverse Voltage	5	V	
Operating Temperature	-40 to + 85		
Storage Temperature	-40 to + 85		
Lead Soldering Temperature [2mm From Body]	260 for 3 Seconds		
Lead Soldering Temperature [5mm From Body]	260 for 5 Seconds		

1. Storage

The storage ambient for the LEDs should not exceed 30 °C temperature or 70% relative humidity.

It is recommended that LEDs out of their original packaging are used within three months.

For extended storage out of their original packaging, it is recommended that the LEDs be stored in a sealed container with appropriate desiccant or in desiccators with nitrogen ambient.

2. Precautions in handling:

- When soldering, leave 2mm of minimum clearance from the resin to the soldering point.
- Dipping the resin to solder must be avoided.
- Correcting the soldered position after soldering must be avoided.

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Electrical Optical Characteristics at Ta=25°C

Parameter	Symbol	Min.	Тур.	Max.	Unit	Test Condition
Radiant Intensity	Ie		30		mW/sr	I _F =50mA (Note 1,3)
Viewing Angle	1/2		65		deg	(Note 2)
Peak Wavelength			940		nm	I _F =20mA
Spectral Line Half- Width			50		nm	I _F =20mA
Forward Voltage	$V_{\rm F}$		1.25	1.5	V	I _F =50mA
Reverse Current	I _R			50	μΑ	V _R =5

Note:

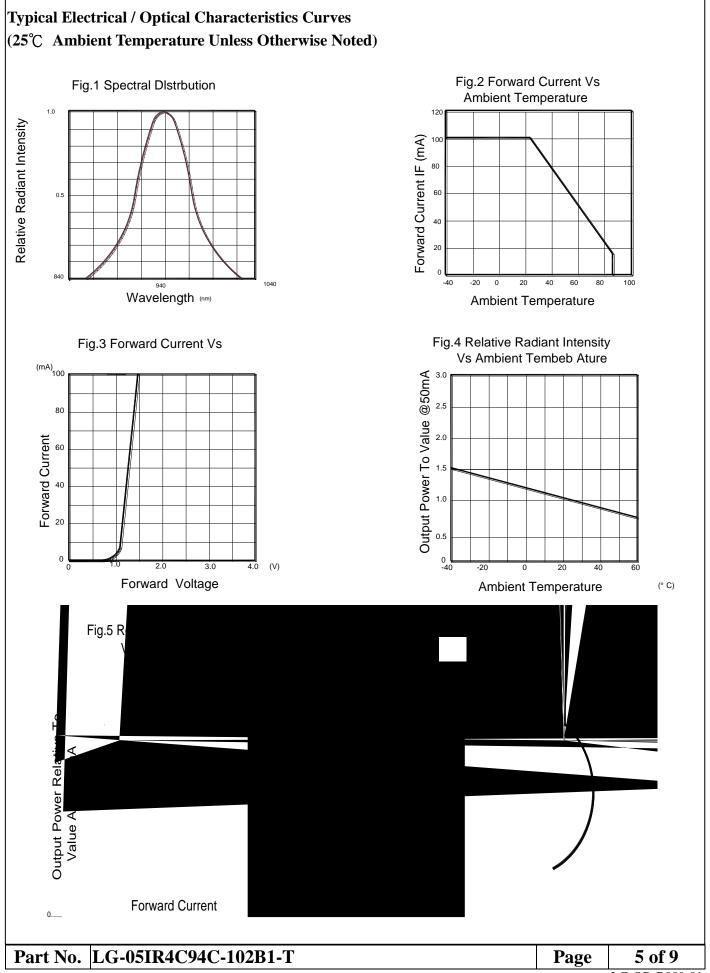
- 1. Point sources of the amount of radiation per unit time in a given direction within the unit solid Angle radiated energy.
- 2.

-axis angle at which the Radiant Intensity is half the axial Radiant Intensity.

3. The Ie guarantee should be added $\pm 15\%$ tolerance.

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